

**AMENDMENTS TO THE SPECIFICATION**

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**ABSTRACT**

The present invention is an electroconductive fine particle, which has a gold coating formed by electroless gold plating on the surface of a nickel undercoating, the amount of nickel dissolved in a dissolution test of the electroconductive fine particle with nitric acid being 30 to 100  $\mu\text{g/g}$ ; a method of producing the electroconductive fine particle, wherein the method allows a reducing agent, causing oxidation reaction on the surface of a nickel undercoating but not causing oxidation reaction on the surface of gold as deposited metal, to be present on the surface of the nickel undercoating thereby reduces a gold salt to deposit gold; and an anisotropic electroconductive material, which comprises the electroconductive fine particle dispersed in a resin binder.